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(71) Applicant: **SHIN KOBE ELECTRIC MACH CO
LTD HITACHI CHEM CO LTD**

(72) Inventor: **NASU HAJIME
HIRAOKA KOICHI
SHIMAZU TORU
AIZAWA TERUKI**

(54) **EPOXY RESIN COMPOSITION AND PREPREG
AND PRINTED CIRCUIT BOARD USING THE
SAME**

(57) Abstract:

PROBLEM TO BE SOLVED: To obtain an epoxy resin composition capable of imparting good flame retardancy substantially without containing halogen atoms when forming an insulating layer by being supported to a sheetlike organic fibrous substrate.

SOLUTION: This epoxy resin composition comprises (A) an epoxy resin without containing a

halogen, (B) a phenolic resin, (C) a thermosetting resin having dihydrobenzoxazine ring, (D) a phosphorus compound and (E) an inorganic filler as essential components. The insulating layer is formed by impregnating the epoxy resin composition into an aramid fibrous substrate (preferably polyparaphenylene terephthalamide fibrous substrate) and supporting thereto. The component (B) is preferably a phenolic novolak resin containing phosphorus atom or nitrogen atom in the molecular structure thereof.

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